

Remarks/Arguments:

Claims 1-8 are pending in the above-identified application. Claims 1 and 3-6 are amended and new claims 7-8 have been added. Accordingly claim 1-8 are presented for reconsideration.

Claims 3 and 6 were rejected under 35 U.S.C. § 112, second paragraph, as being indefinite. Claims 3 and 6 have been appropriately amended. Withdraw of the rejection is respectfully requested.

Claims 1, 3-4 and 6 were rejected under 35 U.S.C. § 103 (a) as being obvious in view of the combination of Abe et al. and Ostrem. Claim 1 is amended to recite features neither disclosed or suggested by the prior art, namely:

... forming an adhesion **reinforced part for fixing the main body to the substrate by heating** and curing the adhesive by sealing the inside of the adhesive with solder part by fusing and solidifying of solder particles contained in the adhesive supplied in the adhesion reinforcing portion. (Emphasis added).

Applicants' exemplary embodiment includes a substrate 1, an electrical component 5 and an adhesion reinforcing portion 7b. Electrical component 5 includes connection terminals 5a disposed at both ends of a main body 5b (Figs. 1C and 1D). The adhesion reinforcing portion 7b includes a solder paste 4. The solder paste 4 is a mixture of metal component containing solder particles and thermosetting adhesive. (Page 7, lines 9-10). Because solder paste 4 of adhesion reinforcing portion 7b is a mixture of a metal component containing solder particles and thermosetting adhesive, solder paste 4 spreads over the main body and **fixes the main body 5b to the substrate 1**. (Page 7, lines 9-16, page 9, line 25 to page 10, line 4 and Fig. 3).

Ostrem discloses a solder fillet 113, a height control pad 111, a body portion 117 and a substrate 115. Body portion 117 is disposed on solder fillet 113. Solder fillet 113 is disposed on height control pad 111. Height control pad 111 is disposed on top of substrate 115. (Fig. 1). That is, solder fillet 113 only contacts body portion 117 for height control and does not spread out and fix body portion 117 to substrate 115. Further, Ostrem recites "... when the portion of solder paste disposed onto the height control pad cools down to a solid structure it maintains the height established in the liquidus stage." That is, the solder paste in Ostrem

maintains its height on the height control pad and does not, therefore, spread and fix body portion 117 to substrate 115. Accordingly, Ostrem does not disclose "... forming an adhesion reinforced part for **fixing the main body to the substrate**," as recited in Applicants' claim 1.

The Office Action readily admits that Abe et al. does not disclose or suggest "... supplying the adhesive to an adhesive reinforcing portion ..." That is, Abe et al. does not make up for the deficiencies described above with respect to Ostrem.

Thus, neither Ostrem, Abe et al., nor their combination disclose or suggest "... forming an adhesion reinforced part for **fixing the main body to the substrate**," as recited in Applicants' claim 1.

Thus, Applicants respectfully submit that claim 1 is allowable over the art of record. Claim 3 depends from claim 1. Accordingly, claim 3 is likewise allowable over the art of record.

Claim 4, while not identical to claim 1, includes features similar to those set forth above with regard to claim 1. Thus, claim 4 is also allowable over the art of record for at least reasons similar to those set forth above with regard to claim 1. Claim 6 depends from claim 4. Accordingly, claim 6 is likewise allowable over the art of record.

Claims 2 and 5 were rejected under 35 U.S.C. § 103 (a) as being obvious in view of the combination of Abe et al., Ostrem and Huang et al. Claims 2 and 5 are allowable, however, because they depend from allowable claims.


New claims 7 and 8 have been added. Basis for new claims 7 and 8 may be found, for example, at page 6, lines 11-18, Figs. 1A-1D and Fig. 3 of the originally filed Application. No new matter has been added.

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In view of the foregoing amendments and remarks, Applicants submit that this Application is in condition for allowance which action is respectfully requested.

Respectfully submitted,



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